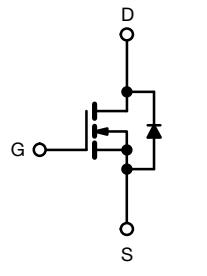
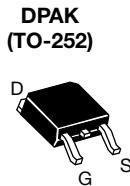


## E Series Power MOSFET



N-Channel MOSFET

<b>PRODUCT SUMMARY</b>	
$V_{DS}$ (V) at $T_J$ max.	850
$R_{DS(on)}$ typ. ( $\Omega$ ) at 25 °C	$V_{GS} = 10$ V      2.38
$Q_g$ max. (nC)	90
$Q_{gs}$ (nC)	11
$Q_{gd}$ (nC)	19
Configuration	Single

### FEATURES

- Low figure-of-merit (FOM)  $R_{on} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Ultra low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**

### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

<b>ORDERING INFORMATION</b>	
Package	DPAK (TO-252)
Lead (Pb)-free and halogen-free	SiHD2N80E-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		$V_{DS}$	800	V
Gate-source voltage		$V_{GS}$	$\pm 30$	
Continuous drain current ( $T_J = 150$ °C)	$V_{GS}$ at 10 V	$I_D$	2.8	A
	$T_C = 25$ °C		1.8	
Pulsed drain current <sup>a</sup>		$I_{DM}$	5	
Linear derating factor			0.5	W/°C
Single pulse avalanche energy <sup>b</sup>		$E_{AS}$	14	mJ
Maximum power dissipation		$P_D$	62.5	W
Operating junction and storage temperature range		$T_J, T_{stg}$	-55 to +150	°C
Drain-source voltage slope	$T_J = 125$ °C	$dV/dt$	70	V/ns
Reverse diode dV/dt <sup>d</sup>			0.13	
Soldering recommendations (peak temperature) <sup>c</sup>	For 10 s		300	°C

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 140$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$  Ω,  $I_{AS} = 0.9$  A
- 1.6 mm from case
- $I_{SD} \leq I_D$ ,  $dI/dt = 100$  A/μs, starting  $T_J = 25$  °C

**THERMAL RESISTANCE RATINGS**

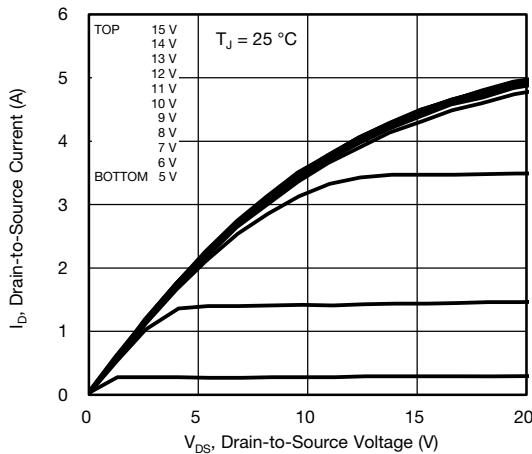
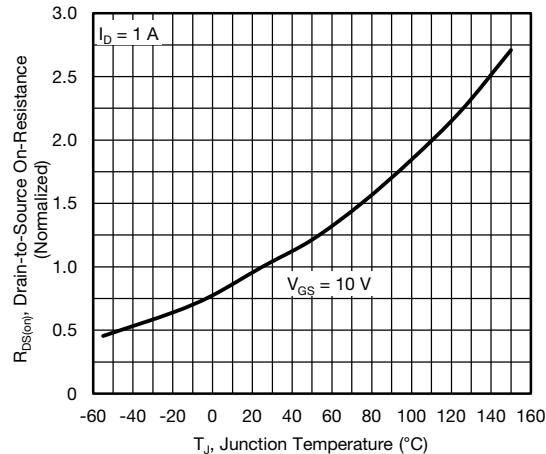
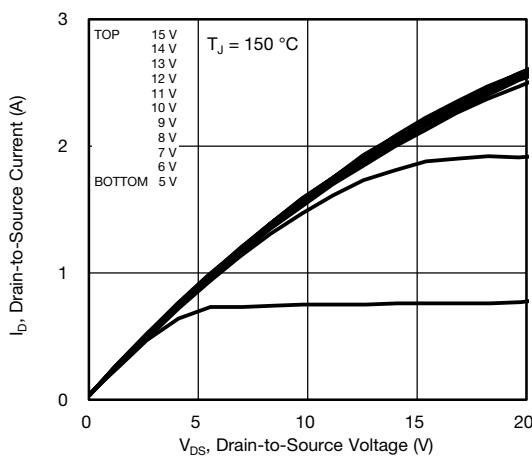
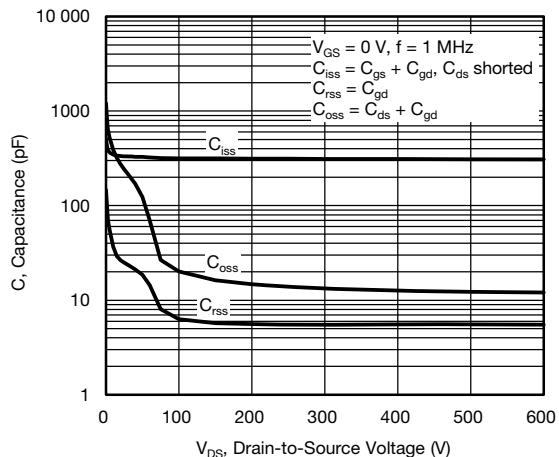
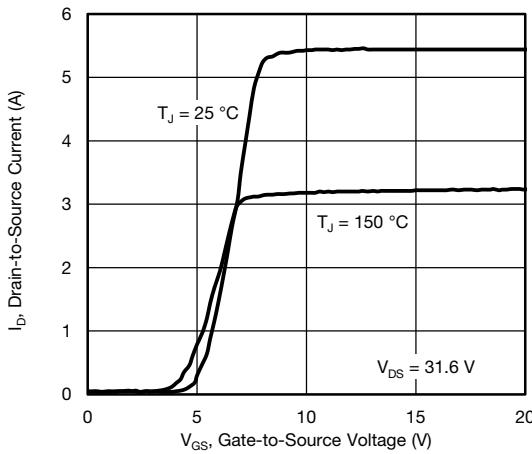
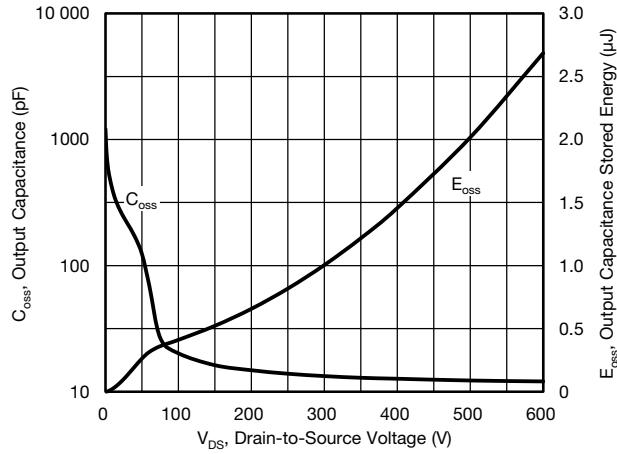
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	62	
Maximum junction-to-case (drain)	$R_{thJC}$	-	2.0	°C/W

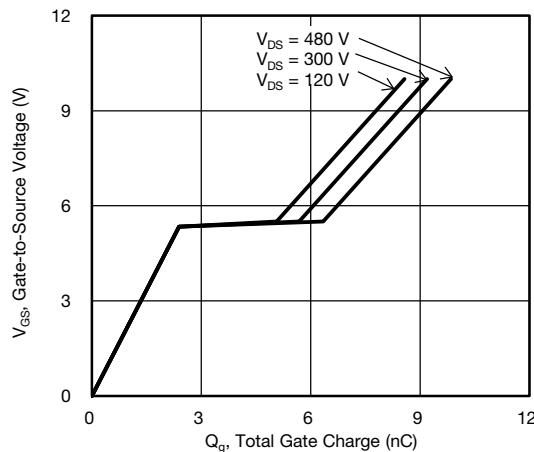
**SPECIFICATIONS ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
<b>Static</b>								
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$		800	-	-	V	
$V_{DS}$ temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25^\circ\text{C}$ , $I_D = 1 \text{ mA}$		-	1.0	-	$\text{V}/^\circ\text{C}$	
Gate-source threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		2.0	-	4.0	V	
Gate-source leakage	$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}$		-	-	$\pm 100$	nA	
		$V_{GS} = \pm 30 \text{ V}$		-	-	$\pm 1$	$\mu\text{A}$	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 800 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	-	1		
		$V_{DS} = 640 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$		-	-	10	$\mu\text{A}$	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 1.0 \text{ A}$	-	2.38	2.75	$\Omega$	
Forward transconductance	$g_{fs}$	$V_{DS} = 30 \text{ V}$ , $I_D = 1.0 \text{ A}$		-	1.0	-	S	
<b>Dynamic</b>								
Input capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 100 \text{ V}$ , $f = 1 \text{ MHz}$		-	315	-	pF	
Output capacitance	$C_{oss}$			-	20	-		
Reverse transfer capacitance	$C_{rss}$			-	6	-		
Effective output capacitance, energy related <sup>a</sup>	$C_{o(er)}$	$V_{DS} = 0 \text{ V}$ to $480 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	13	-		
Effective output capacitance, time related <sup>b</sup>	$C_{o(tr)}$			-	45	-		
Total gate charge	$Q_g$		$V_{GS} = 10 \text{ V}$	$I_D = 1.0 \text{ A}$ , $V_{DS} = 480 \text{ V}$	-	9.8	19.6	nC
Gate-source charge	$Q_{gs}$				-	2.4	-	
Gate-drain charge	$Q_{gd}$				-	3.9	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 480 \text{ V}$ , $I_D = 1.0 \text{ A}$ , $V_{GS} = 10 \text{ V}$ , $R_g = 9.1 \Omega$			-	11	22	ns
Rise time	$t_r$				-	7	14	
Turn-off delay time	$t_{d(off)}$				-	19	38	
Fall time	$t_f$				-	27	54	
Gate input resistance	$R_g$	$f = 1 \text{ MHz}$ , open drain		1.8	3.6	7.2	$\Omega$	
<b>Drain-Source Body Diode Characteristics</b>								
Continuous source-drain diode current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.8	A	
Pulsed diode forward current	$I_{SM}$			-	-	5		
Diode forward voltage	$V_{SD}$	$T_J = 25^\circ\text{C}$ , $I_S = 1 \text{ A}$ , $V_{GS} = 0 \text{ V}$		-	-	1.2	V	
Reverse recovery time	$t_{rr}$	$T_J = 25^\circ\text{C}$ , $I_F = I_S = 1.0 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 25 \text{ V}$		-	278	556	ns	
Reverse recovery charge	$Q_{rr}$			-	0.9	1.8		
Reverse recovery current	$I_{RRM}$			-	5	-	A	

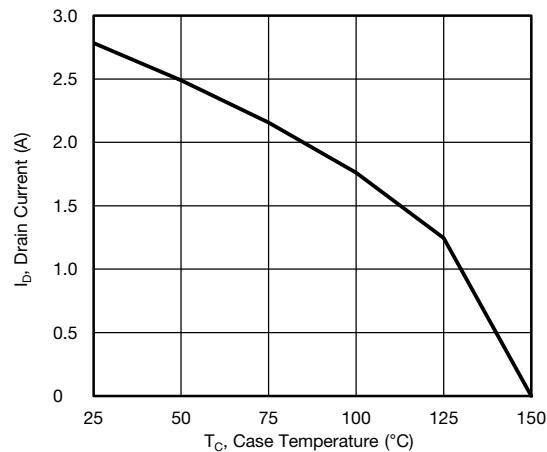
**Notes**

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$   
b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$

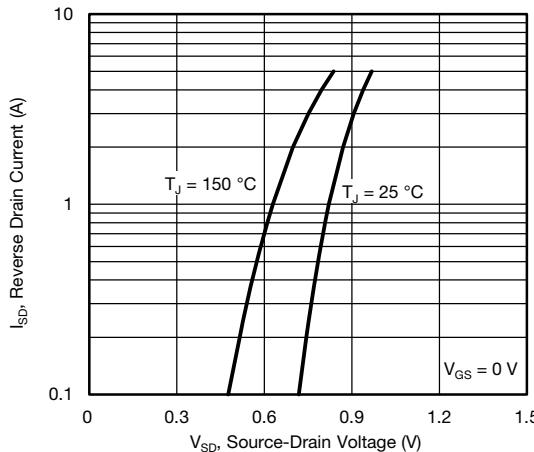
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$**



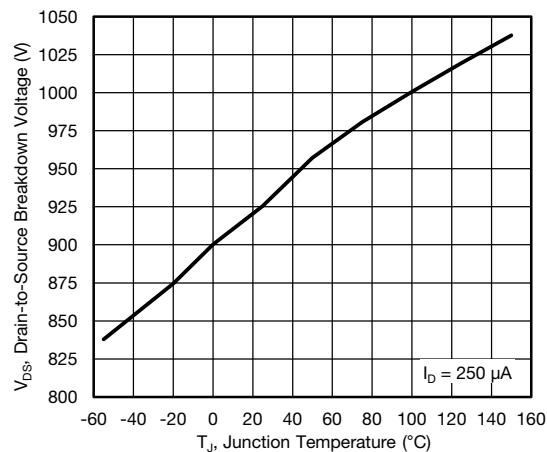
**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**



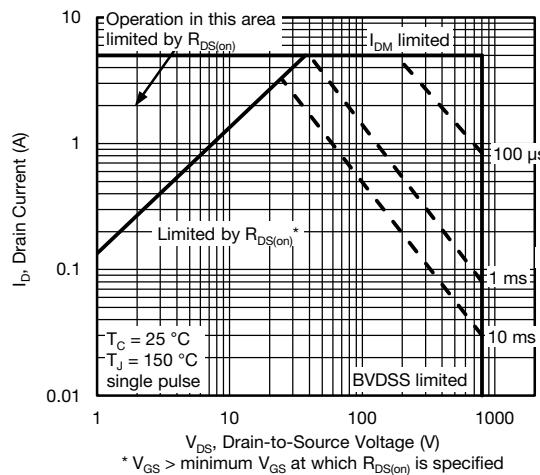
**Fig. 10 - Maximum Drain Current vs. Case Temperature**



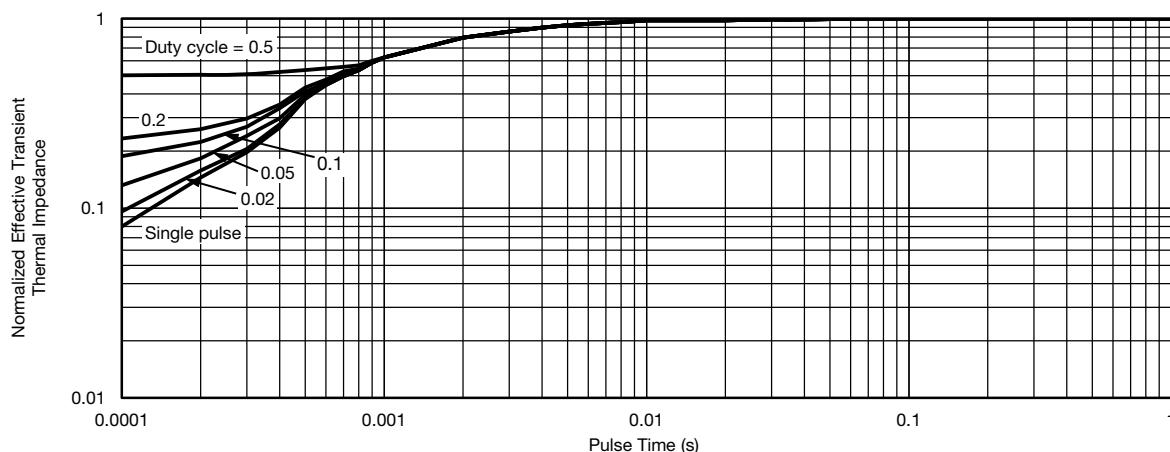
**Fig. 8 - Typical Source-Drain Diode Forward Voltage**



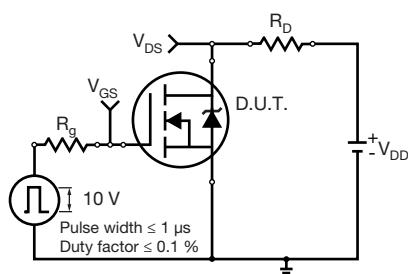
**Fig. 11 - Temperature vs. Drain-to-Source Voltage**



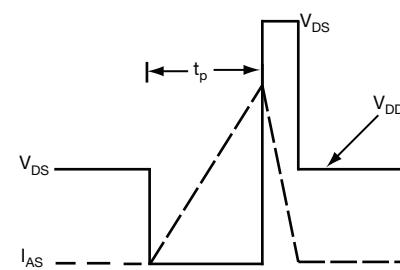
**Fig. 9 - Maximum Safe Operating Area**



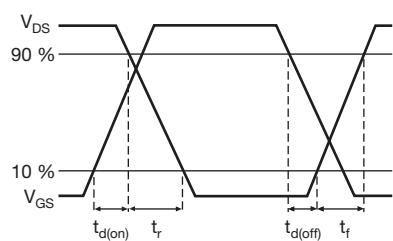
**Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case**



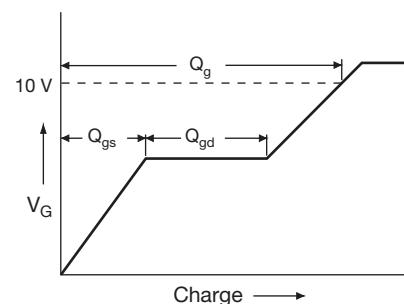
**Fig. 13 - Switching Time Test Circuit**



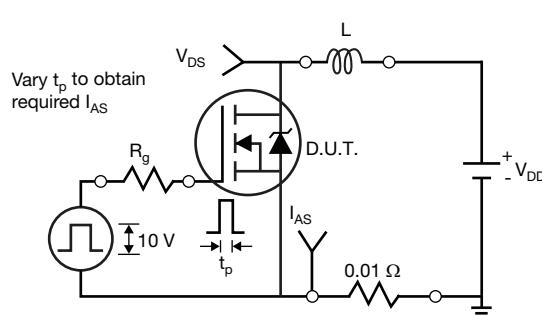
**Fig. 16 - Unclamped Inductive Waveforms**



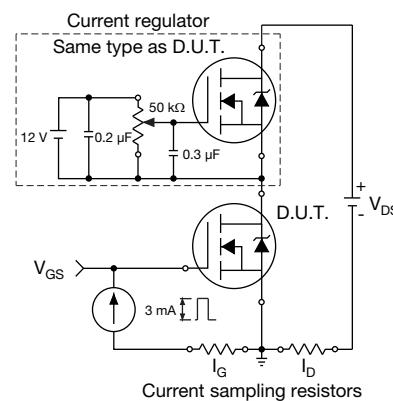
**Fig. 14 - Switching Time Waveforms**



**Fig. 17 - Basic Gate Charge Waveform**



**Fig. 15 - Unclamped Inductive Test Circuit**



**Fig. 18 - Gate Charge Test Circuit**

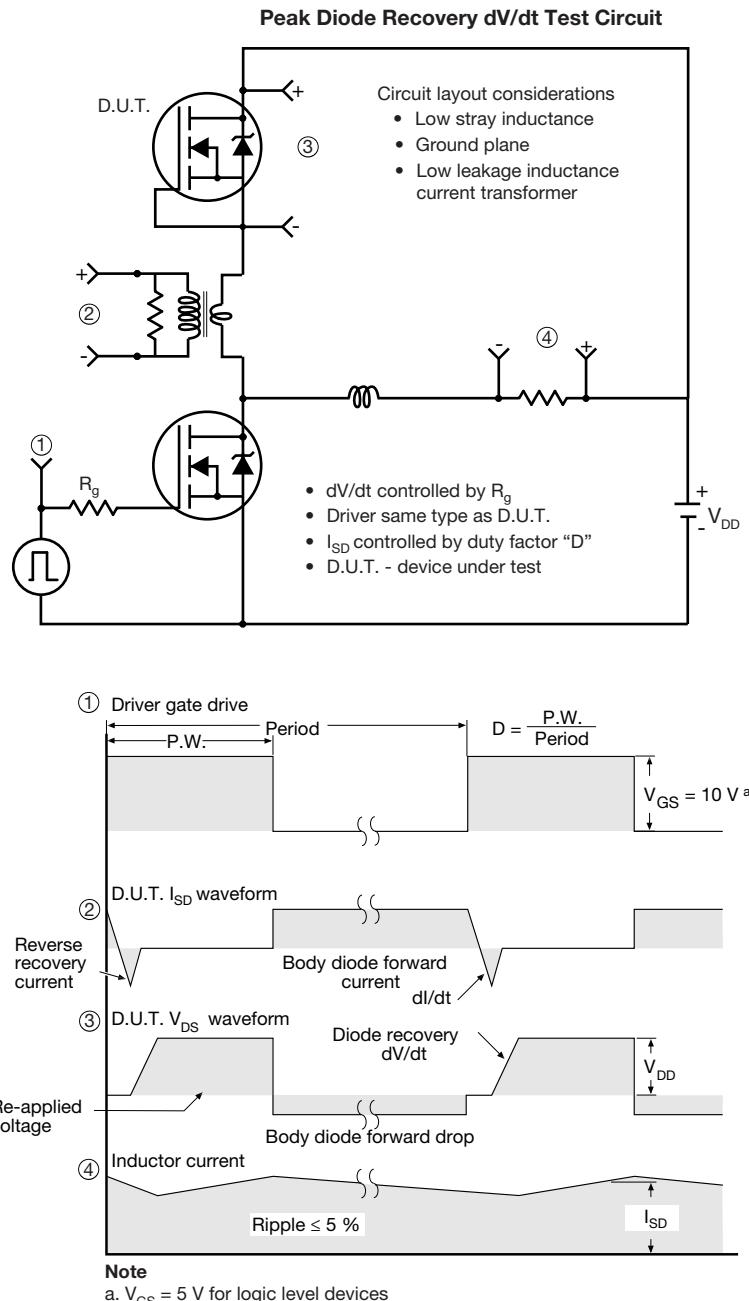
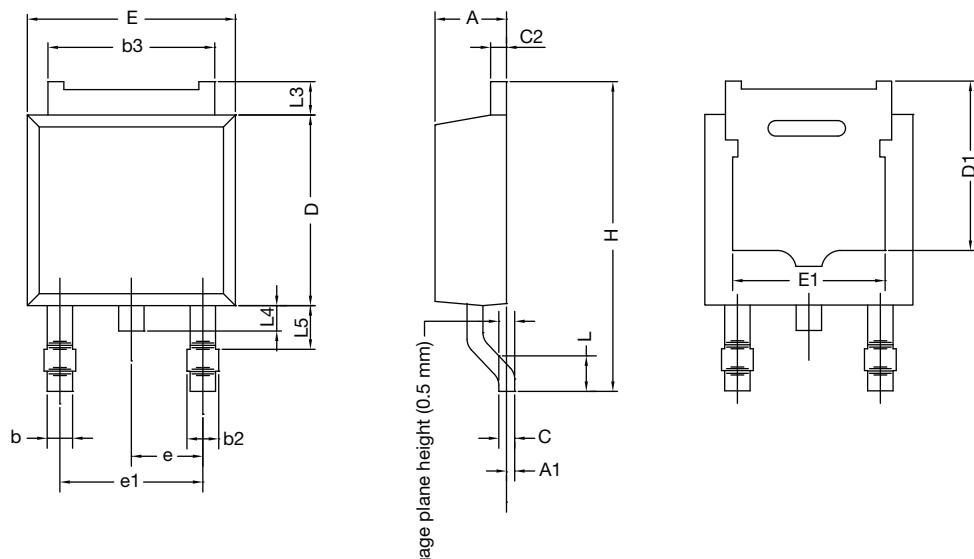


Fig. 19 - For N-Channel

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## TO-252AA Case Outline

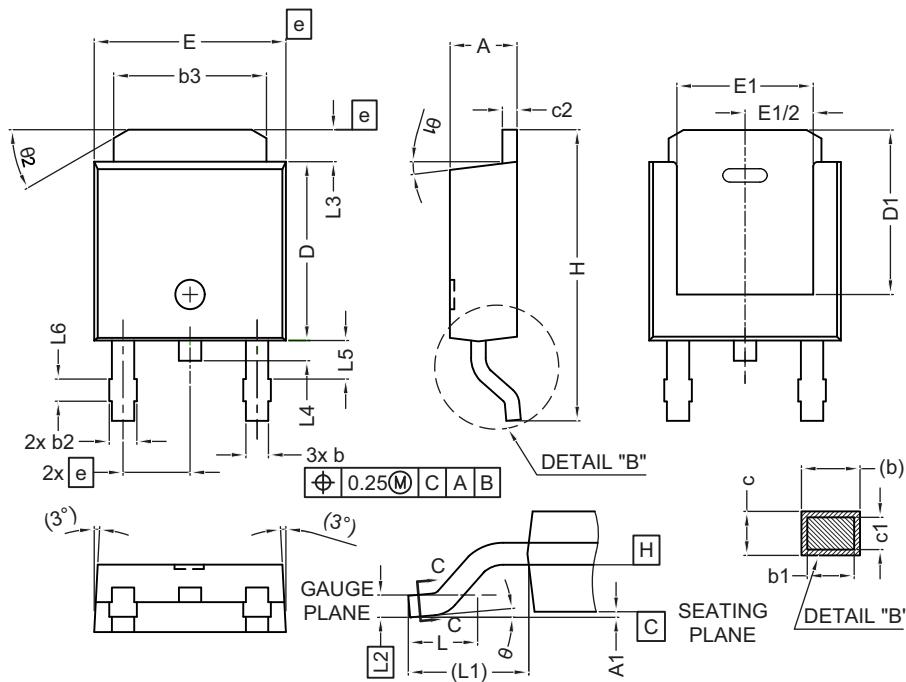
### VERSION 1: FACILITY CODE = Y



<b>MILLIMETERS</b>		
<b>DIM.</b>	<b>MIN.</b>	<b>MAX.</b>
A	2.18	2.38
A1	-	0.127
b	0.64	0.88
b2	0.76	1.14
b3	4.95	5.46
C	0.46	0.61
C2	0.46	0.89
D	5.97	6.22
D1	4.10	-
E	6.35	6.73
E1	4.32	-
H	9.40	10.41
e	2.28 BSC	
e1	4.56 BSC	
L	1.40	1.78
L3	0.89	1.27
L4	-	1.02
L5	1.01	1.52

**Note**

- Dimension L3 is for reference only

**VERSION 2: FACILITY CODE = N**


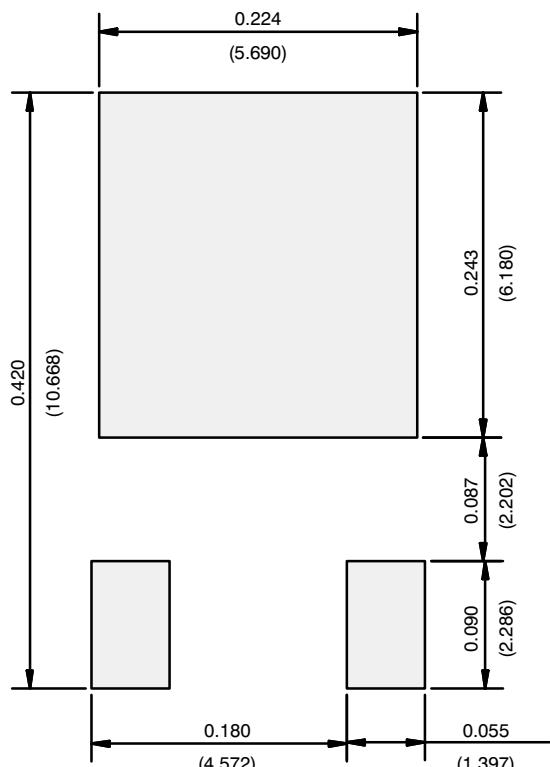
<b>MILLIMETERS</b>		
<b>DIM.</b>	<b>MIN.</b>	<b>MAX.</b>
A	2.18	2.39
A1	-	0.13
b	0.65	0.89
b1	0.64	0.79
b2	0.76	1.13
b3	4.95	5.46
c	0.46	0.61
c1	0.41	0.56
c2	0.46	0.60
D	5.97	6.22
D1	5.21	-
E	6.35	6.73
E1	4.32	-
e	2.29 BSC	
H	9.94	10.34

<b>MILLIMETERS</b>		
<b>DIM.</b>	<b>MIN.</b>	<b>MAX.</b>
L	1.50	1.78
L1	2.74 ref.	
L2	0.51 BSC	
L3	0.89	1.27
L4	-	1.02
L5	1.14	1.49
L6	0.65	0.85
θ	0°	10°
θ1	0°	15°
θ2	25°	35°

**Notes**

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022  
DWG: 5347

**RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**

Recommended Minimum Pads  
Dimensions in Inches/(mm)

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